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(12) **United States Design Patent** (10) **Patent No.:** **US D778,850 S**  
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(54) **SUBSTRATE FOR AN ELECTRONIC CIRCUIT**

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(\*\*) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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USPC ..... **D13/182**

(58) **Field of Classification Search**

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CPC ..... H01L 25/072; H01L 2224/48245;  
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H01L 23/31; H01L 23/3107; H01L  
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C09K 19/00; C09K 19/02; G06F 1/183;  
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33/128; H05K 1/00; H05K 1/11; H05K  
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See application file for complete search history.

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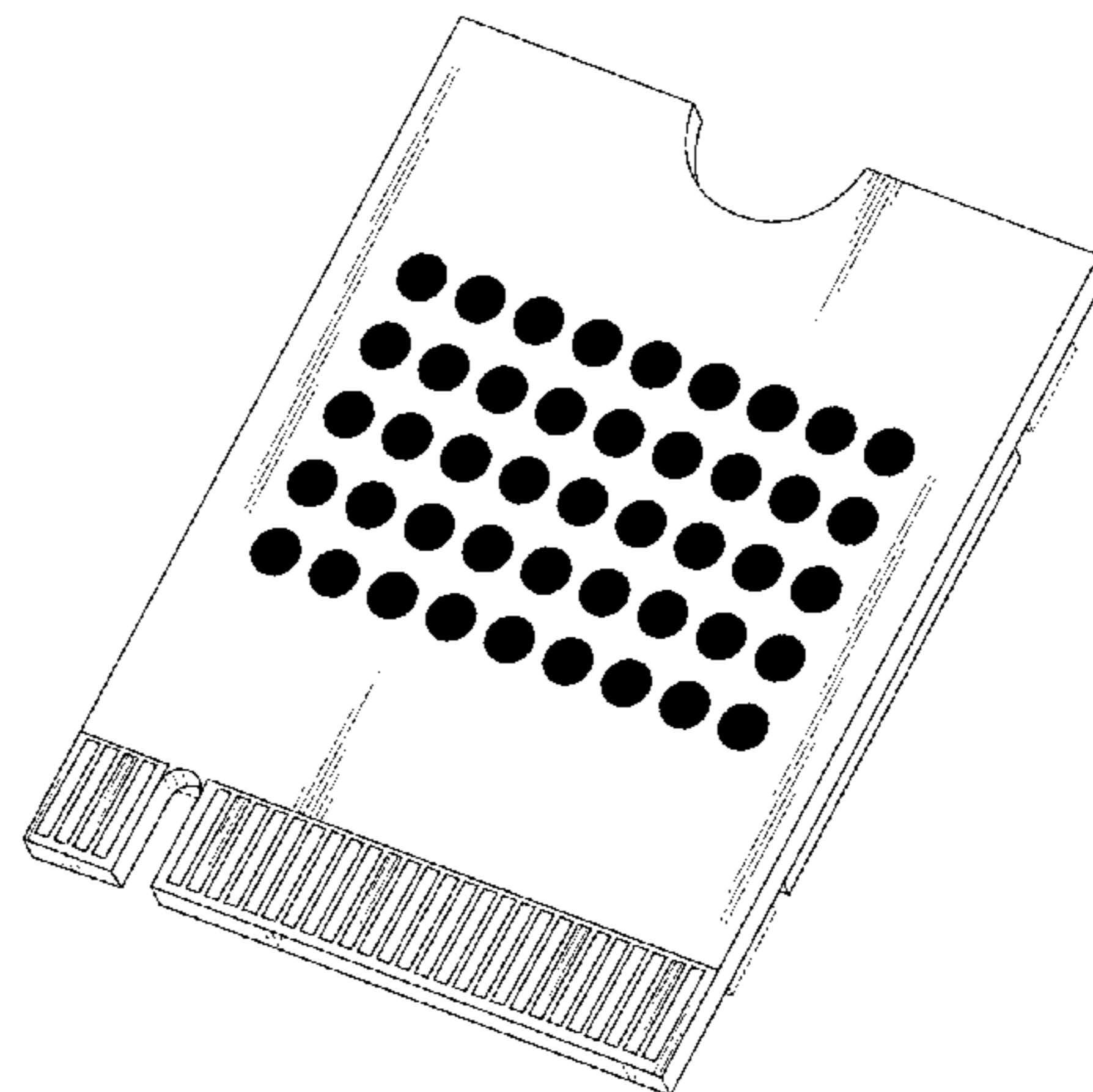
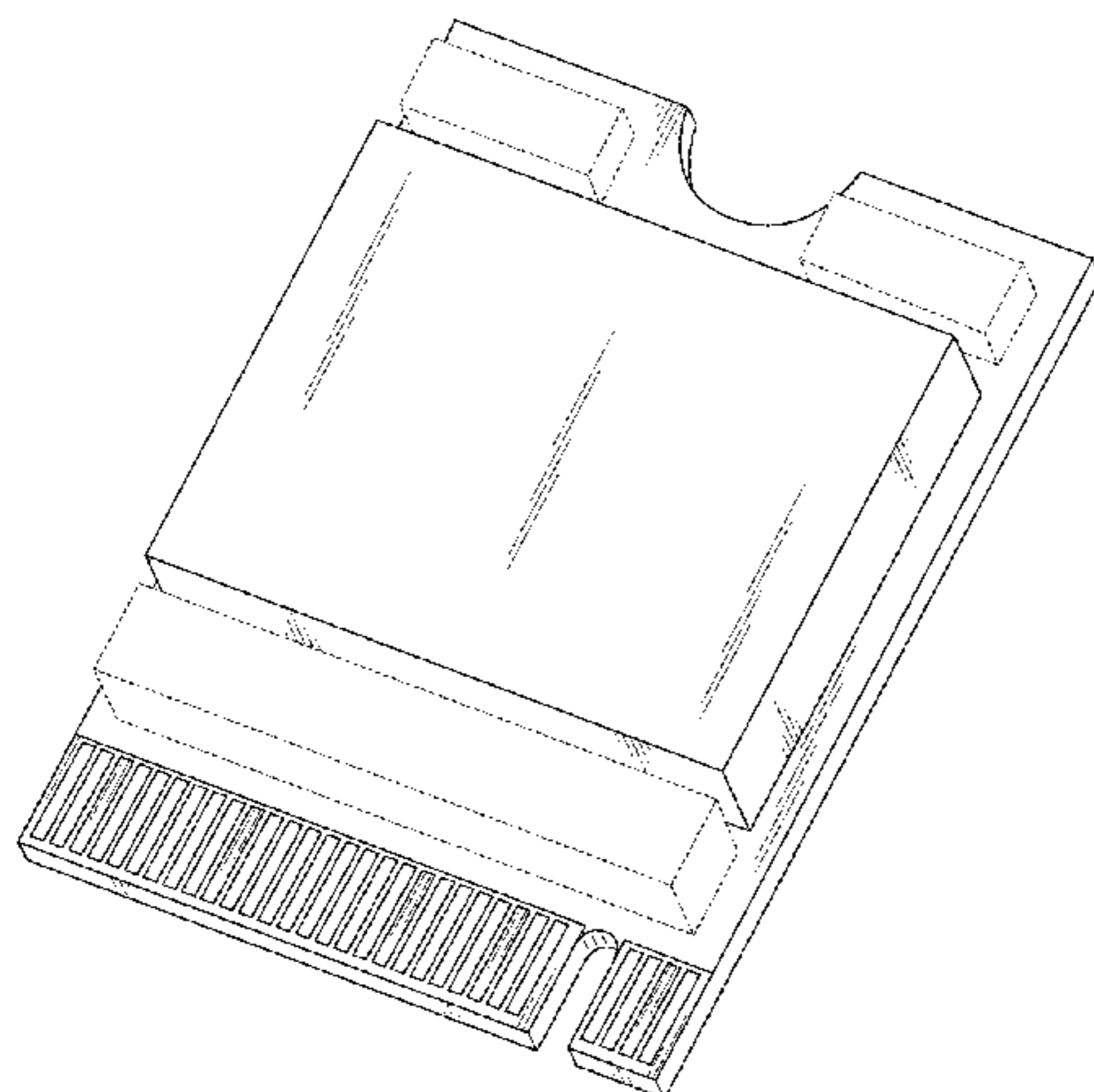
(57) **CLAIM**

The ornamental design for a substrate for an electronic circuit, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a substrate for an electronic circuit showing our new design;  
FIG. 2 is a rear perspective view thereof;  
FIG. 3 is a front elevational view thereof;  
FIG. 4 is a rear elevational view thereof;  
FIG. 5 is a right side elevational view, a left side elevational view being a mirror image thereof;  
FIG. 6 is a top plan view thereof; and,  
FIG. 7 is a bottom plan view thereof.  
The broken lines shown in the drawings represent portions of the substrate for an electronic circuit that form no part of the claimed design.

**1 Claim, 5 Drawing Sheets**



(56)

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Fig. 1

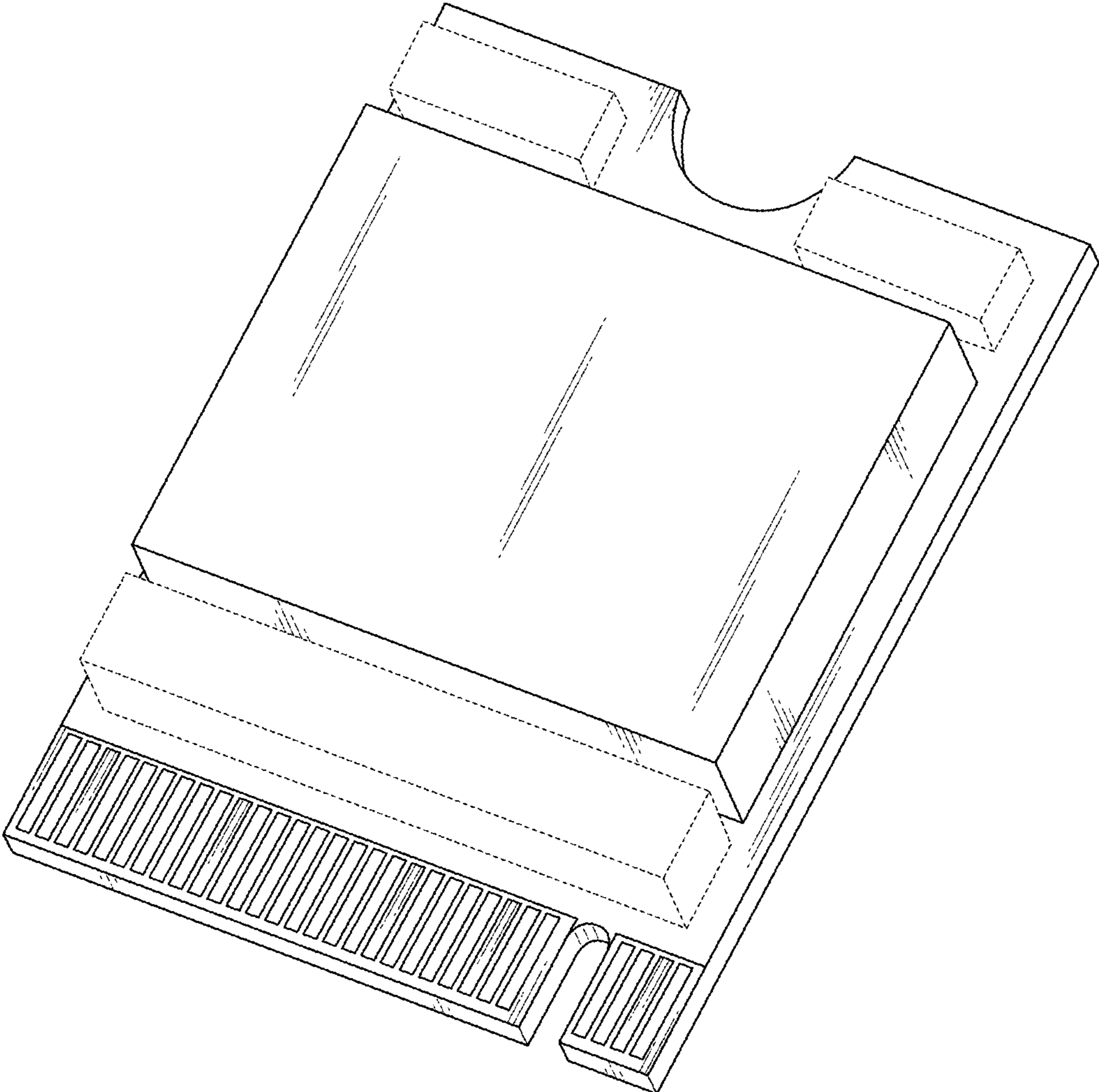


Fig. 2

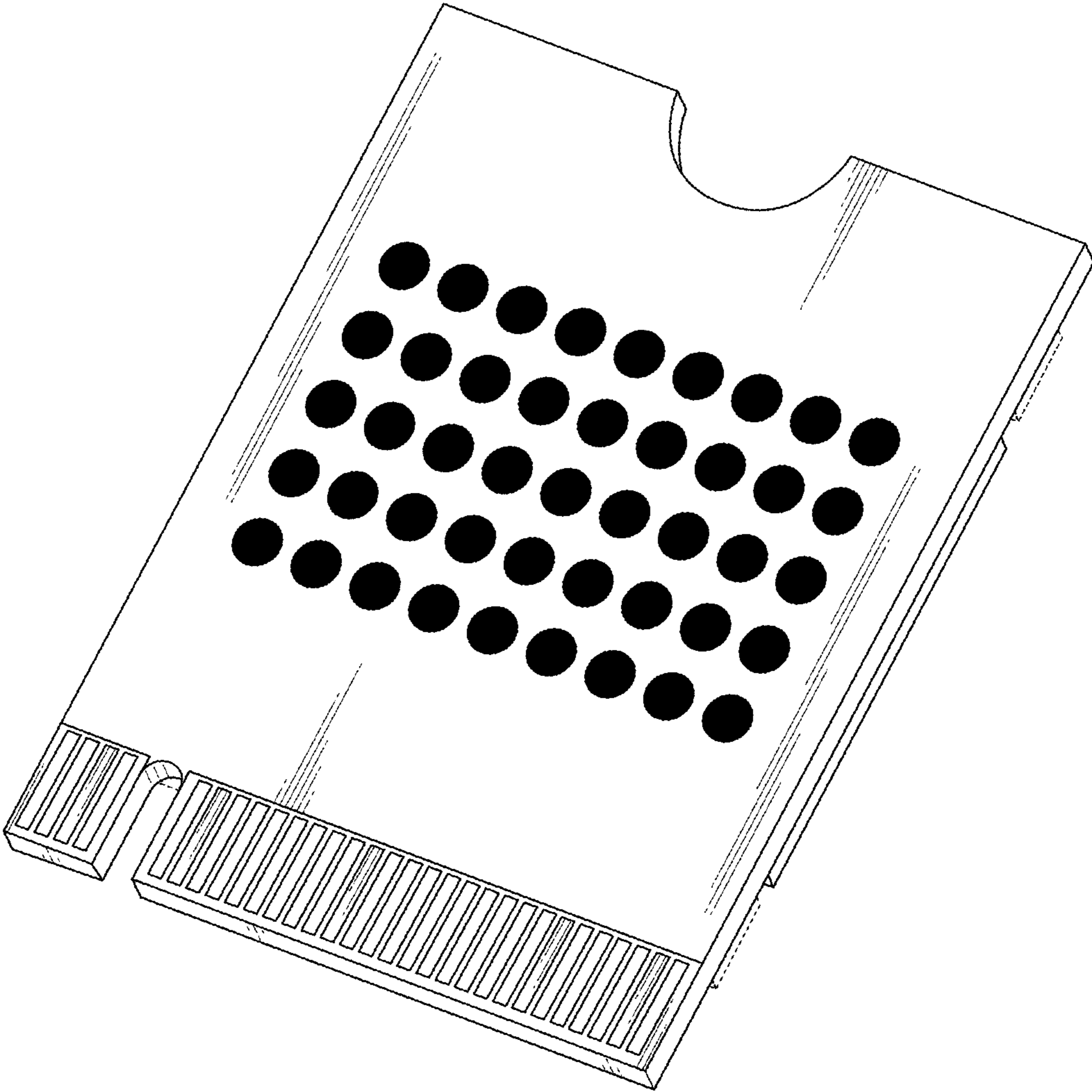




Fig. 3

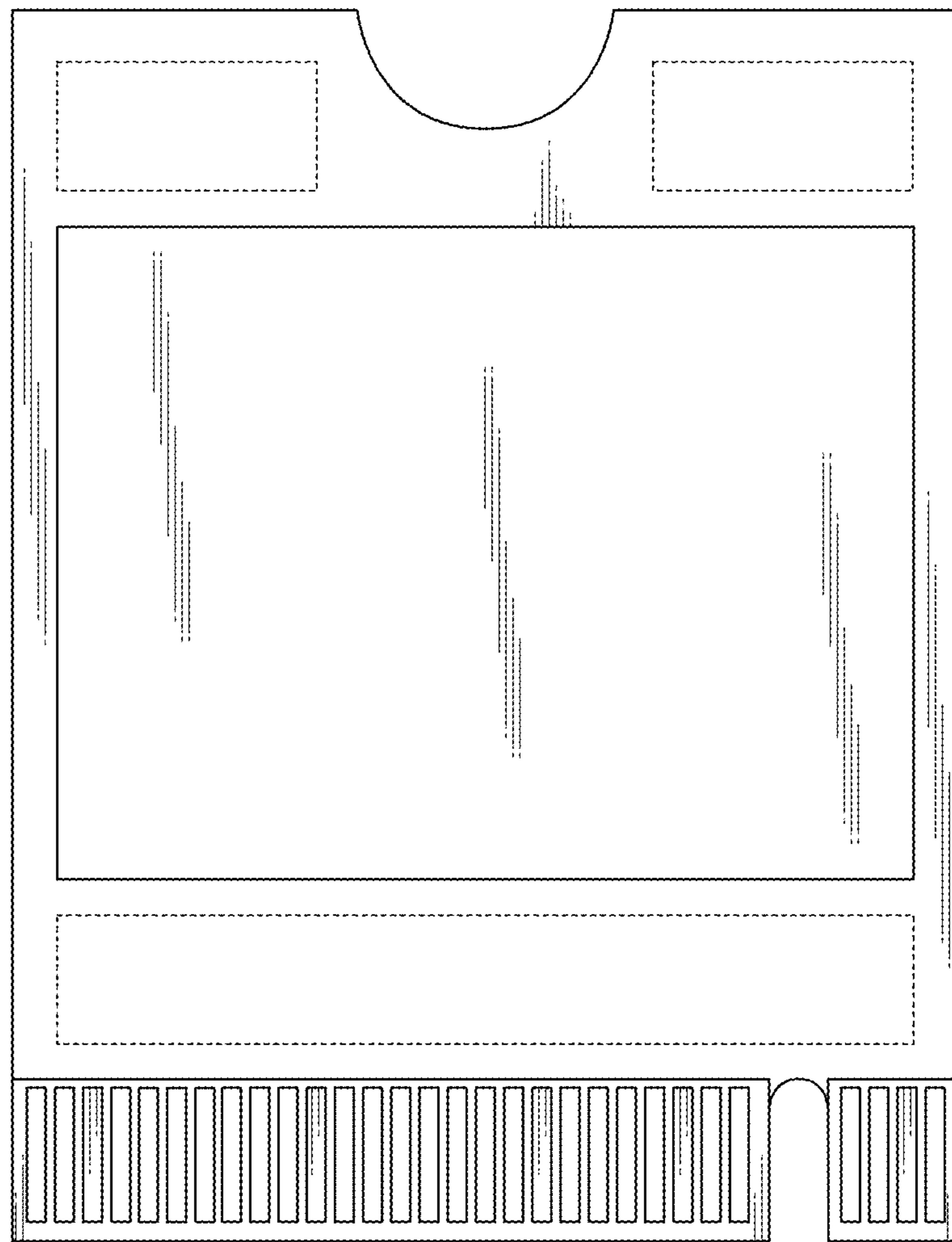


Fig. 4

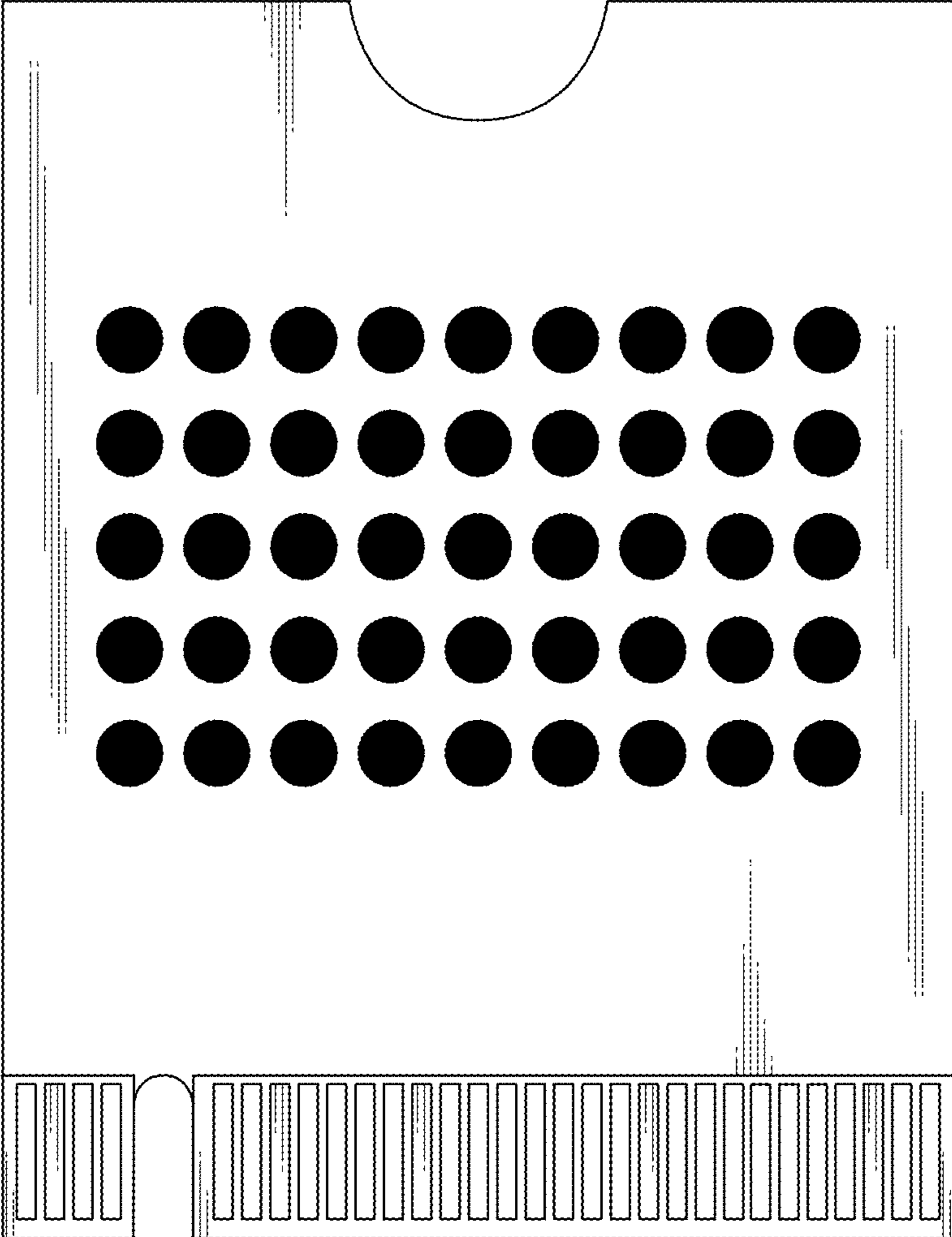


Fig. 5

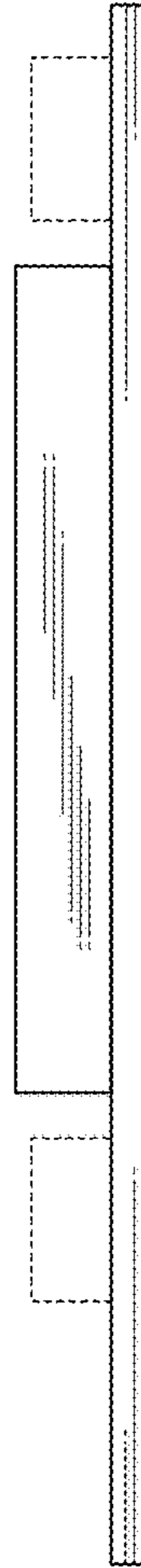


Fig. 6

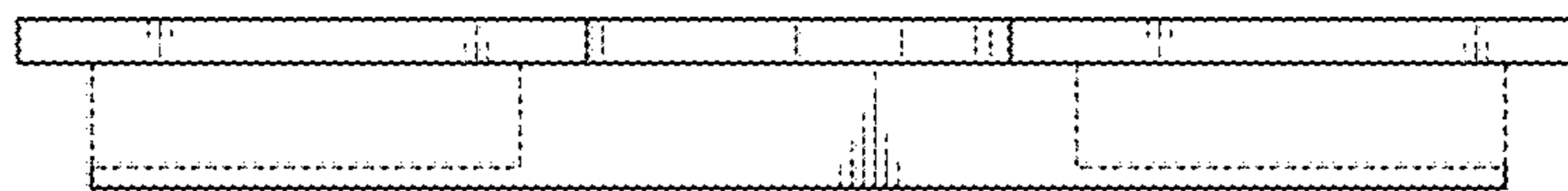


Fig. 7

